Form <b>PTO-1595</b> (Rev. 03-11) QMB No. 0651-0027 (8xp. 03/31/2012)	U.S. DEPARTMENT OF COMMERCE United States Patent and Trademark Offic
RECORDATI	ON FORM COVER SHEET FENTS ONLY
	ice: Please record the attached documents or the new address(es) below.
Name of conveying party(ies):     Yutaka Shimada (12/13/2002) and Hideo     Nagasaka (12/17/2002)	Name and address of receiving party(les)     Name: Sony Corporation
Additional name(a) of conveying party(iss) attached? Yes	Internal Address:  X No Street Address:
3. Nature of conveyance/Execution Date(s):	
- , , -	1-7-1 Konan, Minato-ku Tokyo
Execution Date(s): in parentheses after inventor nar	IABAN
X Assignment Merger Change of Na	ame JAPAN
Security Agreement Joint Research Agreer	menl City:
Government Interest Assignment	State:
Executive Order 9424, Confirmatory License	Country: Zip:
Other	Additional name(s) & address(es) Yes X No attached?
A. Patent Application No.(s) 11/649,055 Additional number	B. Patent No.(s) s attached?  Yes X No
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Bruno Polito LERNER, DAVID, LITTENBER KRUMHOLZ & MENTLIK, LL	
Internal Address; Atty. Dkt.: SONYJP 3.3 952 CG	ТИС
Street Address: 600 South Avenue West	X Authorized to be charged to deposit account
	Enclosed  None required (government interest not affecting title)
City: Westfield	8. Payment Information
· · · · · · · · · · · · · · · · · · ·	7090
Phone Number: 908-654-5000	
Fax Number: 908-654-7866	Deposit Account Number 12-1095
Email Address: ataylor@ldlkm.com	Authorized User Name Bruno Polito
9. Signature:	-
K C	April 3, 2012
Signature	Date
Bruno Polito - 38,580	Total number of pages including cover sheet, attachments, and documents:
Name of Person Signing	sheet, attachments, and documents:

PATENT REEL: 027992 FRAME: 0644 LDLKM

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## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

METHOD AND APPARATUS FOR ADJUSTING OPTICAL PICKUP

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan (hereinafter reference as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and

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said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

LDLKM

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

International Application Number International Filing Date <u>July 16</u>	
U.S. Serial Number	
U.S. Filing Date	
This assignment executed on the	e dates indicated below.
Yutaka SHIMADA	December 13 2002
Name of first or sole inventor	Date
Tokyo, Japan Residence of first or sole inventor	
Yutaka Shineda Signature of first or sole inventor	
Signature of first or sole inventor	Execution date of U.S. Patent Application
	December 17, 2002
Hideo NAGASAKA	Judge of the first
Name of second inventor	Date
Kanagawa, Japan	
Residence of second inventor	
24 der Magazaka. Signature of second inventor	
Signature of second inventor	Execution date of U.S. Patent Application

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**PATENT** REEL: 027992 FRAME: 0646